

# MS52XX (RoHS<sup>\*</sup>)

# **SMD PRESSURE SENSOR**



- 1 and 12 bar absolute pressure range
- Uncompensated
- Piezoresistive silicon micromachined sensor
- Surface mount 7.6 x 7.6 mm
- · Low noise, high sensitivity, high linearity
- RoHS-compatible & Pb-free\*

### **DESCRIPTION**

The MS52XX SMD pressure sensor series is designed for pressure sensor systems with highest demands on resolution and accuracy. The device consists of a silicon micromachined pressure sensor die mounted on a 7.6 x 7.6 mm ceramic carrier protected by a metal cap. The MS52XX can be delivered in a highly sensitive version giving a maximal output voltage or in a highly linear version giving a linear output voltage directly proportional to the applied pressure.

Full Scale	High Sensitivity Version		High Linearity Versions		
Pressure	Product Code	Full Scale Span / Linearity	Product Code	Full Scale Span / Linearity	
1 bar	MS5201-AN	240 mV / ±0.2% FS	MS5201-BN	150 mV / ±0.05% FS	
12 bar			MS5212-BM	150 mV / ±0.05% FS	

#### **FEATURES**

- Low cost SMD ceramic package
- · High reliability, low drift

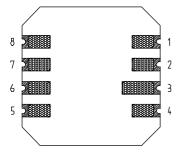
- -40 °C to +125 °C operation range
- Optional: Gel protection against humidity and water

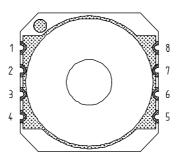
# **APPLICATIONS**

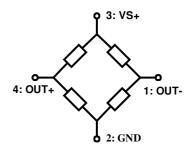
- Absolute pressure sensor systems
- High resolution altimeters, variometers
- Barometers

- Engine controls
- Diver's computers
- Tire pressure

#### PIN CONFIGURATION







<sup>\*</sup> The European RoHS directive 2002/95/EC (Restriction of the use of certain Hazardous Substances in electrical and electronic equipment) bans the use of lead, mercury, cadmium, hexavalent chromium and polybrominated biphenyls (PBB) or polybrominated diphenyl ethers (PBDE).

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1



# **PIN DESCRIPTION**

Pin Name	Pin No.	Function
OUT-	1	Negative output voltage of Wheatstone bridge
GND	2	Ground
VS+	3	Supply voltage of Wheatstone bridge
OUT+	4	Positive output voltage of Wheatstone bridge

# **ABSOLUTE MAXIMUM RATINGS**

Parameter		Symbol	Conditions	Min	Max	Unit
Supply voltage		VS+	Ta = 25°C		20	V
Storage temperature		Ts		-40	+125	°C
Overpressure	MS5201-AN			-	5	
	MS5201-BN	Р	Ta = 25 °C	-	10	bar
	MS5212-BM			-	30	



#### **ELECTRICAL CHARACTERISTICS**

#### **HIGH SENSITIVITY VERSION**

(VS+ = 5 V; Ta = 25 %)

	Parameter	Min	Тур	Max	Unit	Notes
	Operating pressure range	0	-	1	bar	
	Full-scale span (FS)	190	240	290	mV	
	Sensitivity	190	240	290	mV/bar	
	Linearity	-	±0.15	±0.4	% FS	1, 6
	Operating temperature range	-40	-	125	°C	
MCE201 AN	Zero pressure offset	-40	0	40	mV	
MS5201-AN	Pressure hysteresis	1	-	±0.20	% FS	2, 6
	Temperature hysteresis	1	0.3	0.8	% FS	3, 6
	Repeatability	1	-	±0.20	% FS	4, 6
	Bridge resistance	3.0	3.4	3.8	kΩ	
	Temperature coefficient of resistance Temperature coefficient of span Temperature coefficient of offset	+2'400 -1'500 -80	2'900 -1'900 -	+3'300 -2'300 +80	ppm/°C ppm/°C μV/°C	5, 6 5, 6 5, 6

# **NOTES**

- 1) Deviation at one half full-scale pressure from the least squares best line fit over pressure range.
- 2) Maximum difference of output voltage after 1 pressure cycle at any pressure within the operating pressure range.
- 3) Maximum difference in offset after one thermal cycle from -40 °C to +125 °C.
- 4) Same as 2) after 10 pressure cycles.
- 5) Slope of the endpoint straight line from 25 °C to 60 °C.
- 6) Not 100% tested.



# **ELECTRICAL CHARACTERISTICS (CONT.)**

#### **HIGH LINEARITY VERSIONS**

(VS + = 5 V; Ta = 25 %)

4

	Parameter	Min	Тур	Max	Unit	Notes
	Operating pressure range	0	-	1	bar	
MS5201-BN	Full-scale span (FS)	120	150	180	mV	
WISSZUT-DIN	Sensitivity	120	150	180	mV/bar	
	Linearity	-	±0.05	±0.2	% FS	1, 6
	Operating pressure range	0	-	12	bar	
MS5212-BM	Full-scale span (FS)	120	150	180	mV	
IVISSZ I Z-BIVI	Sensitivity	10	12.5	15	mV/bar	
	Linearity	-	±0.05	±0.2	% FS	1, 6
	Operating temperature range	-40	-	125	°C	
	Zero pressure offset	-40	0	40	mV	
	Pressure hysteresis	-	-	±0.2	% FS	2, 6
All Danses	Temperature hysteresis	-	0.3	0.8	% FS	3, 6
All Ranges	Repeatability	-	-	±0.2	% FS	4, 6, 7
	Bridge resistance	3.0	3.4	3.8	kΩ	
	Temperature coefficient of resistance Temperature coefficient of span Temperature coefficient of offset	+2'400 -1'500 -80	2'900 -1'900 -	+3'300 -2'300 +80	ppm/°C ppm/°C μV/°C	5, 6 5, 6 5, 6

#### **NOTES**

- 1) Deviation at one half full-scale pressure from the least squares best line fit over pressure range.
- 2) Maximum difference of output voltage after 1 pressure cycle at any pressure within the operating pressure range.
- 3) Maximum difference in offset after one thermal cycle from -40 °C to +120 °C.
- 4) Same as 2) after 10 pressure cycles.
- 5) Slope of the endpoint straight line from 25 °C to 60 °C.
- 6) Not 100% tested.
- 7) MS5212-BM: Max. 0.3% FS.



#### **APPLICATION INFORMATION**

#### **GENERAL**

The MS52XX is a miniaturised absolute pressure sensor series that has been designed for surface mounting applications. Its main advantages are the high reliability of the semiconductor sensor and a design which makes it suitable for applications requiring small-scale and cost-efficient solutions.

The sensor element of the MS52XX consists of a micromachined silicone membrane with Pyrex glass wafer-bonded under vacuum to the backside for reference pressure. Implanted resistors make use of the piezo-resistive effect to sense pressure applied to the membrane. The sensor is mounted in a special process allowing best-offset stability making the part suitable for direct PCB assembly.

Typical applications for this miniaturised pressure sensor MS52XX are altitude measurements and the measurement of atmospheric reference pressure in medical and industrial equipment as well as in automotive and household applications, consumer electronics and pneumatics.

Full Scale Pressure	High Sensitivity Version (MS5201-AN)	High Linearity Versions (MS5201-BN and MS5212-BM)
1 bar	Variometer, Altimeter, Barometer	High End Altimeter, Medical Instrumentation
12 bar		Pneumatic Brake, Diving Computer

#### LIGHT SENSITIVITY

The MS52XX is sensitive to sunlight, especially to infrared light sources. This is due to the strong photo effect of silicon. As the effect is reversible there will be no damage, but the user has to take care that in the final product the sensor cannot be exposed to direct light during operation. This can be achieved for instance by placing mechanical parts with holes in such way that light cannot go trough.

#### **CONNECTION TO PCB**

The package outline of the module allows the use of a flexible PCB to connect it. This can be important for applications in watches and other special devices, and will also reduce mechanical stress on the device. For applications subjected to mechanical shock, it is recommended to enhance the mechanical reliability of the solder junctions by covering the rim or the corners of MS52XX ceramic substrate with glue or Globtop-like material.

#### **SOLDERING**

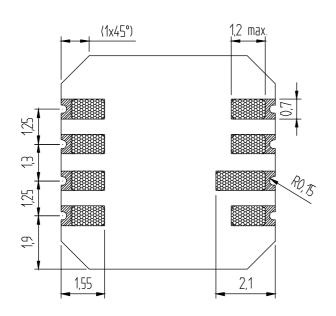
Please refer to the application note AN808 for all soldering issues.

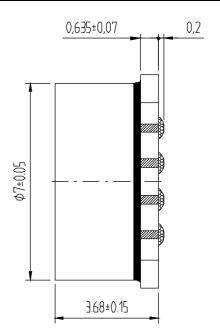
#### **CLEANING**

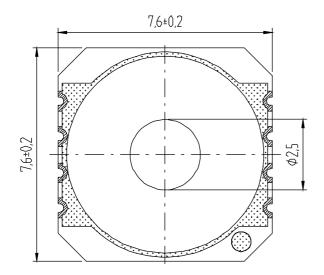
The MS52XX has been manufactured under cleanroom conditions. Each device has been inspected for the homogeneity and the cleanness of the silicone gel. It is therefore recommended to assemble the sensor under class 10'000 or better conditions. Should this not be possible, it is recommended to protect the sensor opening during assembly from entering particles and dust. To avoid cleaning of the PCB, solder paste of type "no-clean" shall be used. **Cleaning might damage the sensor.** 



# **PACKAGE OUTLINES**







#### Notes:

- 1) All dim. in mm
- 2) General tolerance ±0.1
- 3) Cap centering: ±0.15 from the center of the ceramic.



Dielectric

Solder



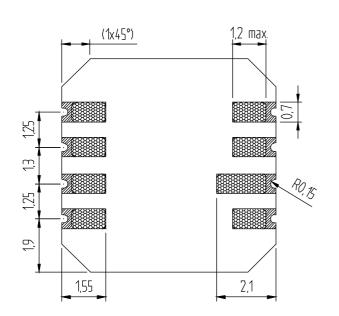
Contact pads

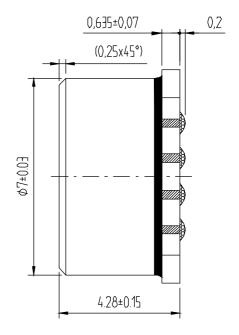


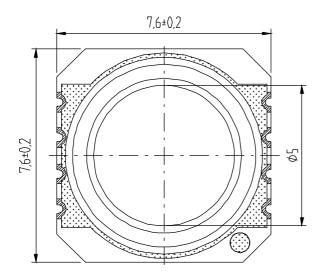
Device package outlines of **MS5201-AN** and **MS5201-BN** (Metal cap with nickel finish, gel protection of bonding wires)



# **PACKAGE OUTLINES (CONT.)**







#### Notes: 1) All dim. in mm

- 2) General tolerance ±0.1
- 3) Cap centering: ±0.15 from the center of the ceramic.





Contact pads

Salder

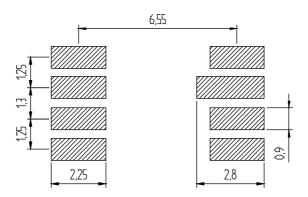


Device package outlines of MS5212-BM (Stainless steel cap, no gel protection of bonding wires)



#### RECOMMENDED PAD LAYOUT

Recommended pad layout for soldering of the MS52xx on a printed circuit board



# **ORDERING INFORMATION**

Product Code	Product	ArtNr.	Package	Comment	
MS5201-AN	Pressure sensor 1 bar High sensitivity	325201002	SMD hybrid with solder bumps, metal cap with nickel finish,		
MS5201-BN	Pressure sensor 1 bar High linearity	325201000	drop of gel on sensor, no gel protection of the bonding wires		
MS5212-BM transparent gel	Pressure sensor 12 bar	325212001	SMD hybrid with solder bumps, Stainless steel cap,	Same sensor for both articles, Only the gel protection changes	
MS5212-BM white gel	High linearity	325212002	Gel protection of sensor and bonding wires		

FACTORY CONTACTS			

#### NOTICE

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